


MATERIAL DECLARATION SHEET



Material Number	3681S - L			
Product Line	Precision Potentiometer			
Compliance Date	May 3, 2006			
RoHS Compliant	Yes	MSL	N/A	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Substrate	Alumina	2.52	Aluminum Oxide	1344-28-1	95	26.732	28.139
				Silicon Oxide	7631-86-9	2	0.563	
				Magnesium Oxide	1309-48-4	2	0.563	
				Calcium Oxide	1305-78-8	1	0.281	
2	Termination Ink	Ink	0.003	Silver	7440-22-4	87	0.029	0.033
				Palladium	7440-05-3	5.5	0.002	
				Lead Borosilicate	65997-17-3	6.5	0.002	
				Lead Monoxide	1317-36-8	0.5	0.0002	
3	Resistive Ink X2	Ink	0.0030	Ruthenium Dioxide	12036-10-1	35	0.012	0.033
				Calcium Silicate borate glass	10101-39-0	46	0.015	
				Silver	7440-22-4	7	0.002	
				Titanium dioxide	13463-67-7	5	0.002	
				Manganese dioxide	1313-13-9	6	0.002	
				Copper Oxide	1317-39-1	1	0.0003	
4	Cover Snap-In X2	Polyphenylene ether	2.75	Polyphenylene ether	25134-01-4	99	15.200	15.354
				Carbon Black	1333-86-4	1	0.154	

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5	Button X2	Acetal Resin	0.6	Polyoxymethylene Homopolymer	7440-44-0	94	6.298	6.700
				Stabilizer		2	0.134	
				Pigment		2	0.134	
				Carbon Black	1333-86-4	2	0.134	
6	Housing Push Button	Polyphenylene ether	1.75	Polyphenylene ether	25134-01-4	99	30.401	30.708
				Carbon Black	1333-86-4	1	0.307	
7	Spacer	PBT	0.005	Glass	65997-17-3	30	0.167	0.558
				Poly(butylene terephthalate)	30965-26-5	65	0.363	
				Antimony Oxide	1309-64-4	5	0.028	
8	Torsion Spring	Metal	0.1998	Iron	7439-89-6	94	2.097	2.231
				Carbon	7440-44-0	1	0.022	
				Manganese	7439-96-5	1	0.022	
				Silicon	7440-21-3	1.2	0.027	
				Chromium	7440-47-3	1.8	0.040	
				Copper	7440-50-8	1	0.022	
		Plating	0.002	Zinc	7440-66-6	100	0.0223	0.022
9	Detent Spring	Beryllium Copper	0.033	Copper	7440-50-8	98.1	0.361	0.368
				Silicon	7440-21-3	0.2	0.001	
				Beryllium	7440-41-7	1.5	0.006	
				Aluminum	7429-90-5	0.2	0.001	
10	Wheel Counter	PBT	0.9	Glass	65997-17-3	30	3.015	10.050
				Poly(butylene terephthalate)	30965-26-5	65	6.532	
				Antimony Oxide	1309-64-4	5	0.502	
11	Terminal Plated X3	Brass	0.48	Copper	7440-50-8	70	3.752	5.360
				Zinc	7440-66-6	30	1.608	
		Plating	0.005	Tin	7440-31-5	100	0.056	0.056

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12	Contact Spring	Spacer Strip	0.00756	Nickel	7440-02-0	18	0.015	0.084
				Copper	7440-50-8	55	0.0464	
				Zinc	7440-66-6	27	0.023	
		Strip Laminated	0.003	Copper	7440-50-8	70	0.023	0.033
				Zinc	7440-66-6	30	0.010	
				Nickel	7440-02-0	18	0.0318	
		Wire	0.01584	Copper	7440-50-8	65	0.1150	0.177
				Zinc	7440-66-6	17	0.030	
				Siloxanes and Silicones, di-Me, di-Ph	68083-14-7	68.9	0.063	
Lithium Stearate	4485-12-5	25.3	0.023					
Silane, dichlorodimethyl- reaction products with silica	68611-44-9	4.7	0.004					
Diphenylamine	122-39-4	0.89	0.001					
		Total weight	8.955					

This Document was updated on: Jun 11, 2007

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemptions used: lead in glass (exemption 5) & lead in copper alloys (exemption 6)